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(54) **DISPLAY PANEL**

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(57) **ABSTRACT**

The embodiment of the present application provides a display panel. The display panel includes a driver substrate and a light emitting device bonded to and disposed on the driver substrate. The driver substrate includes a driver circuit and a first power line. The first power line includes a conductive pad. The light emitting device includes a first soldering pad and a second soldering pad. The first soldering pad overlaps and is bonded to the conductive pad. The second soldering pad is electrically connected to the driver circuit. The embodiment of the present application overlaps and bonds the opaque first soldering pad to the first power line, particularly overlaps and bonds the first soldering pad to the conductive pad. Therefore, an overlapping area between the first soldering pad and the first power line is increased.

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